

Fig. 1

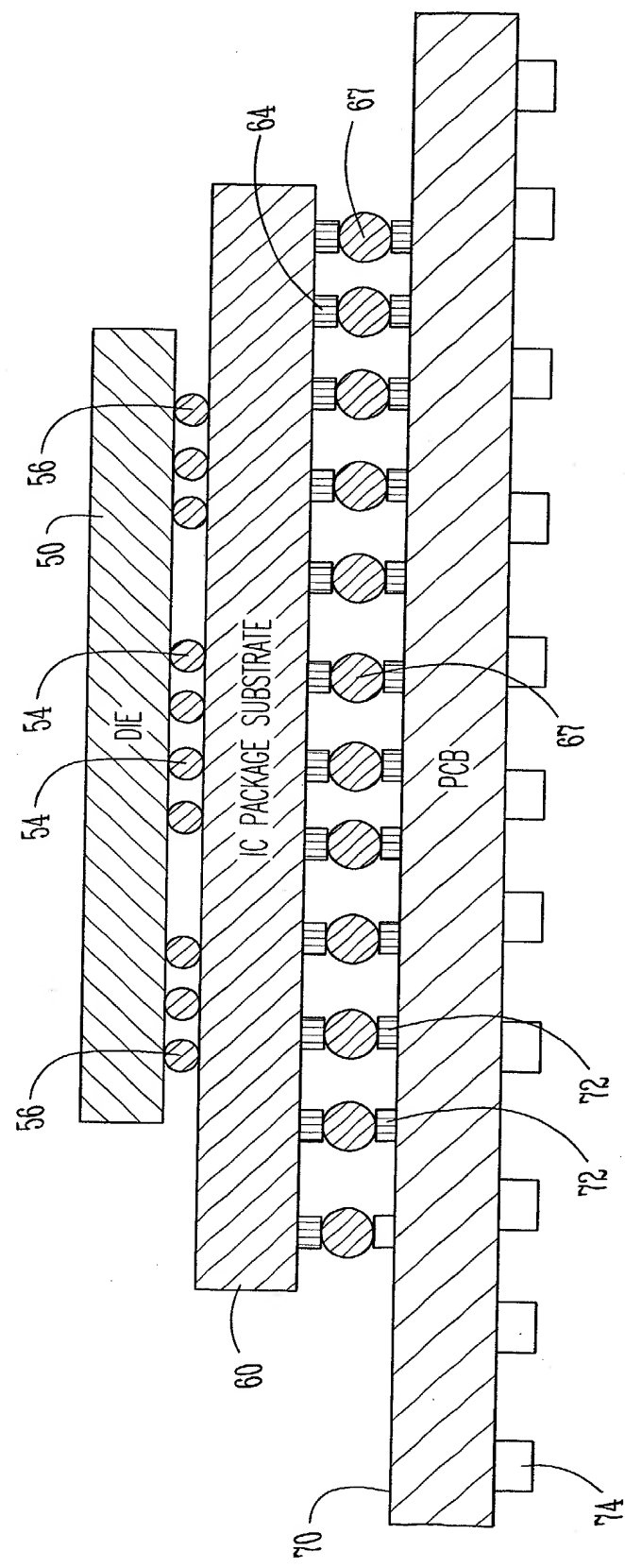


Fig. 2
(Prior Art)

TOP SECRET

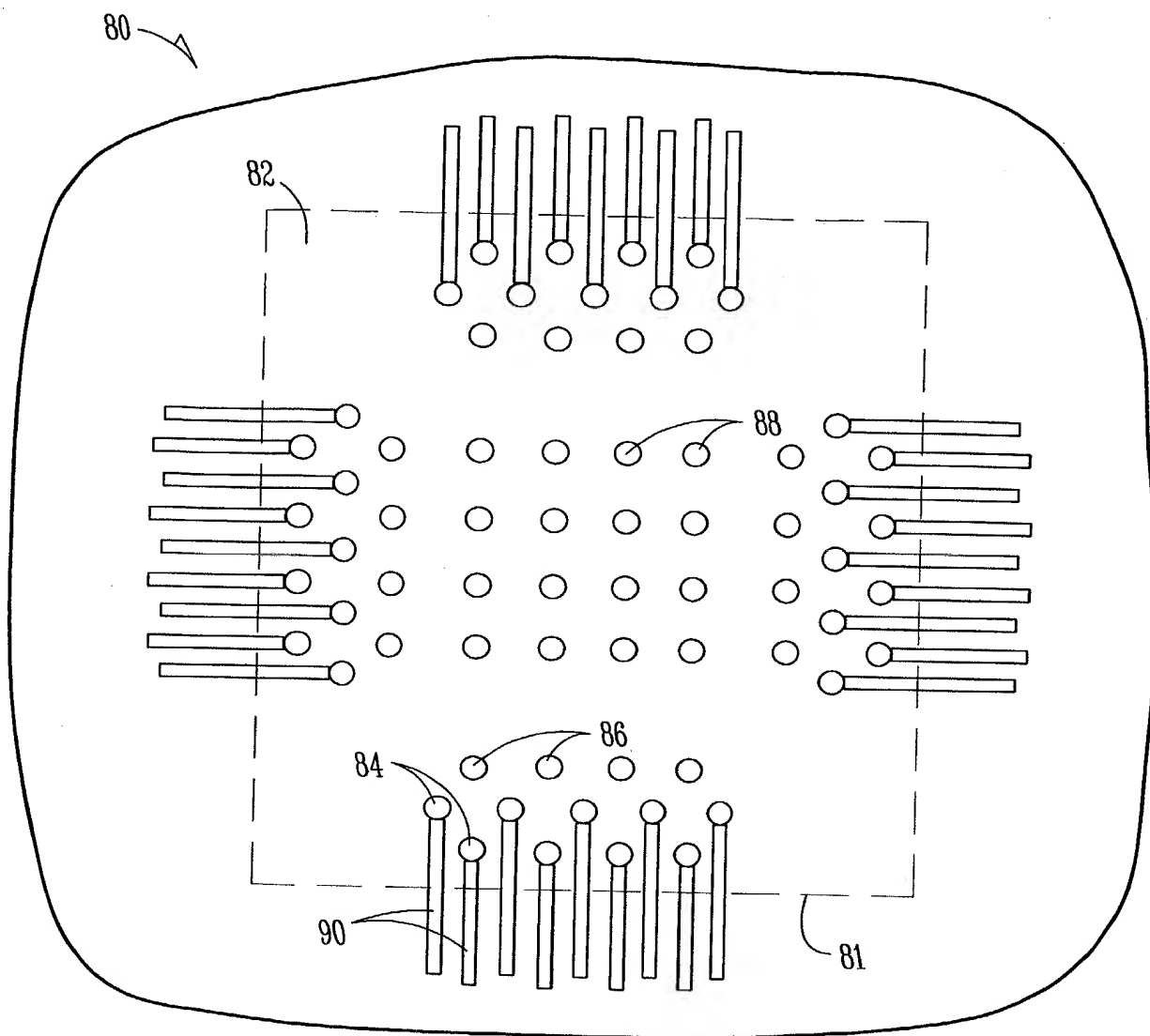


Fig. 3
(Prior Art)

095838-054604

APPROVED	O.G. FIG.	TITLE:
BY	CLASS	SUBCLASS
DRAFTSMAN		

ELECTRONIC PACKAGE WITH HIGH DENSITY INTERCONNECT AND ASSOCIATED METHODS
 INVENTORS NAME: Tee Onn Chong et al.
 DOCKET NO.: 884.419US1

4/12

100 ↗

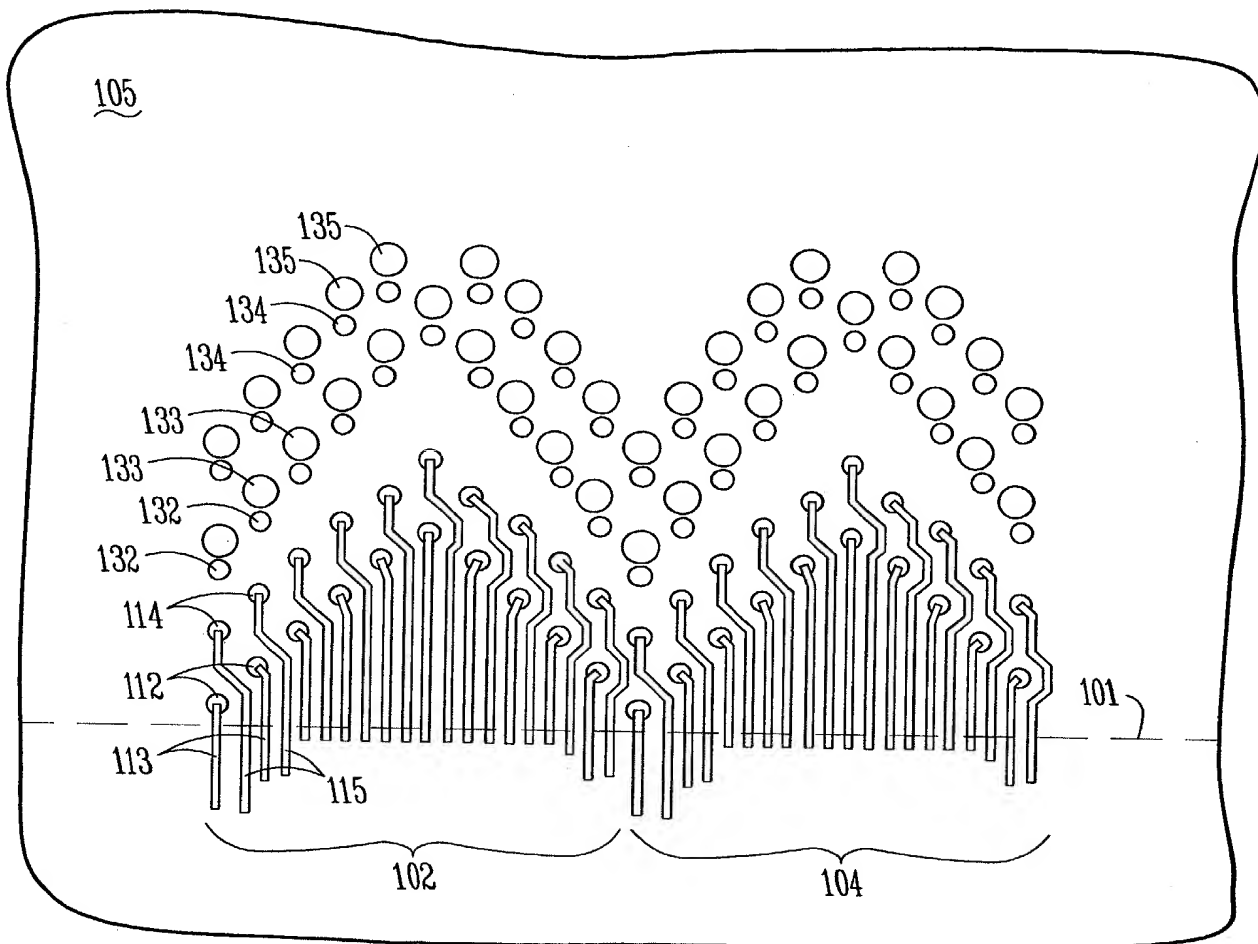


Fig. 4

5/12

150

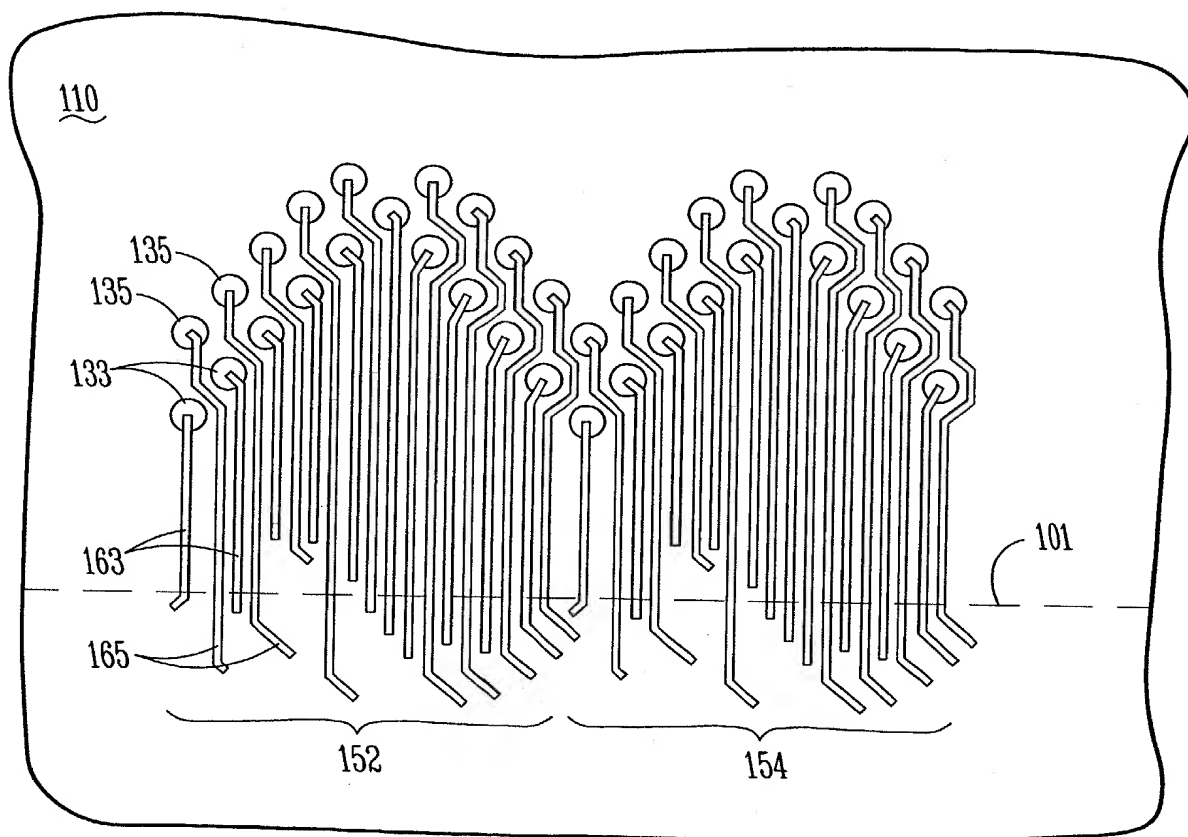


Fig. 5

0958230 051401
 TEE ONN CHONG

APPROVED	O. G. FIG.	TITLE:
BY	CLASS	SUBCLASS
CRAFTSMAN		

ELECTRONIC PACKAGE WITH HIGH DENSITY INTERCONNECT AND ASSOCIATED METHODS
 INVENTORS NAME: Tee Onn Chong et al.
 DOCKET NO.: 884.419US1

6/12

200

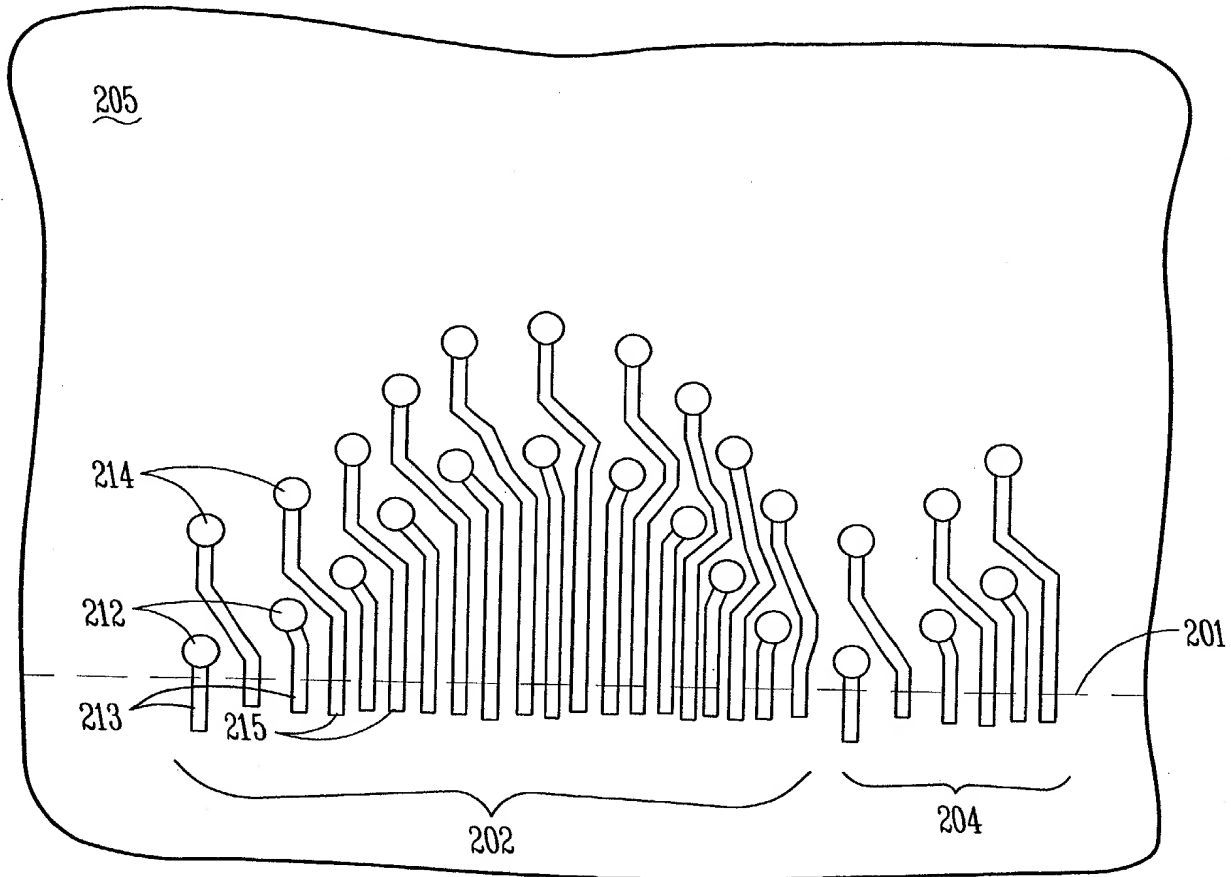


Fig. 6

096939 051001

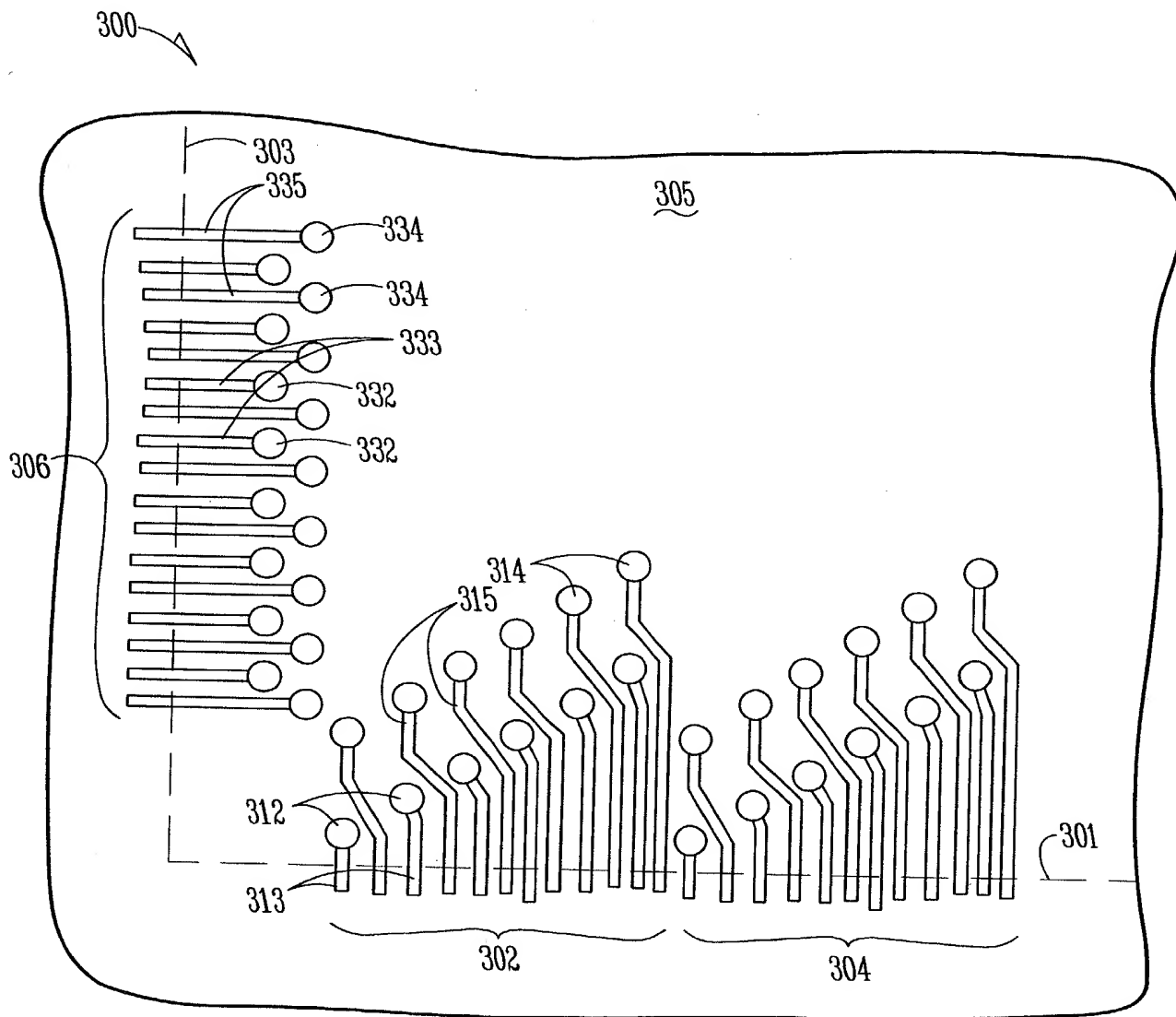


Fig. 7

350 ↗

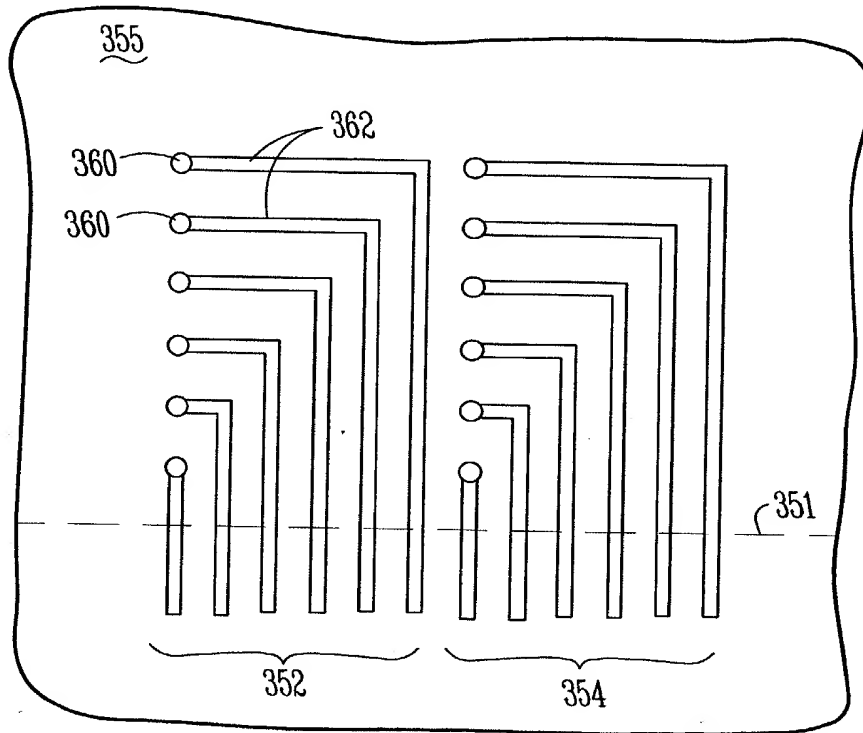


Fig. 8

9/12

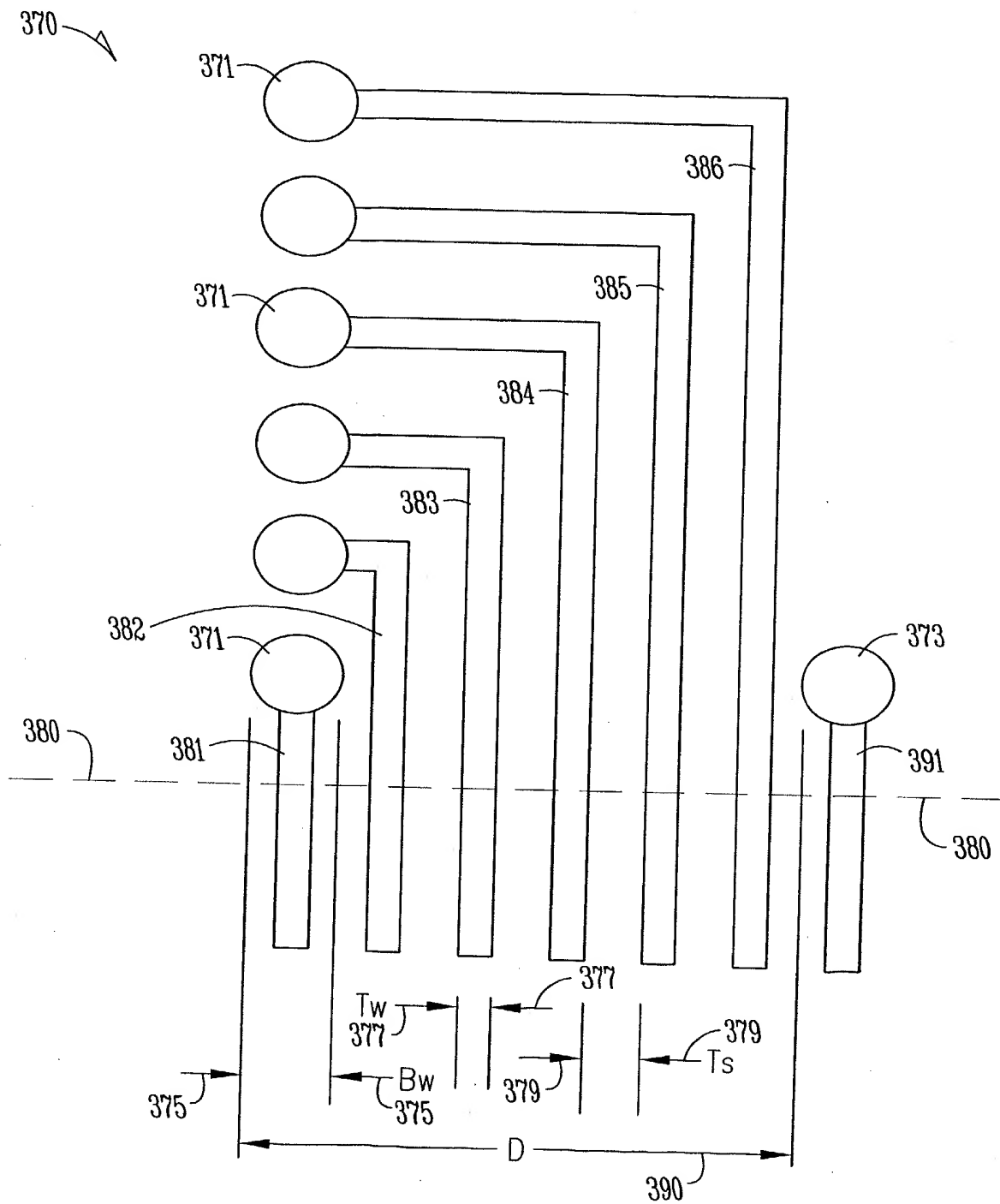


Fig. 9

10/12

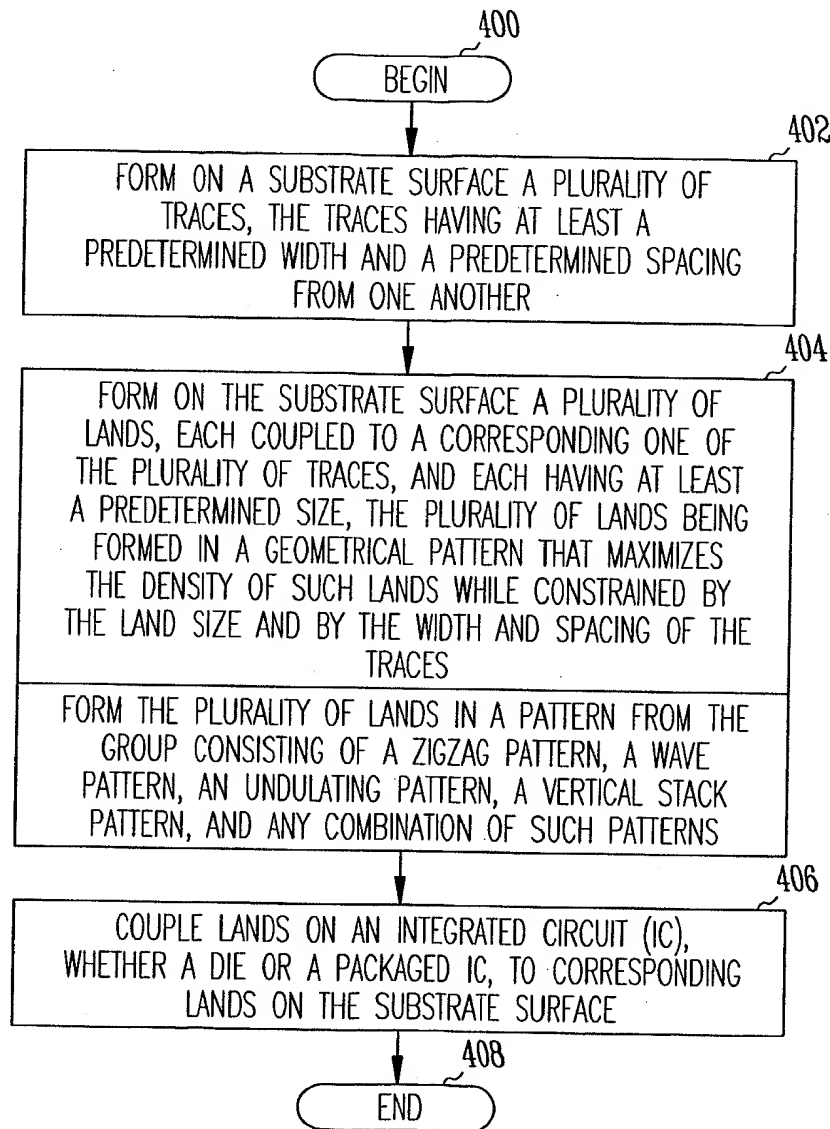


Fig. 10

00858238-051501

11/12

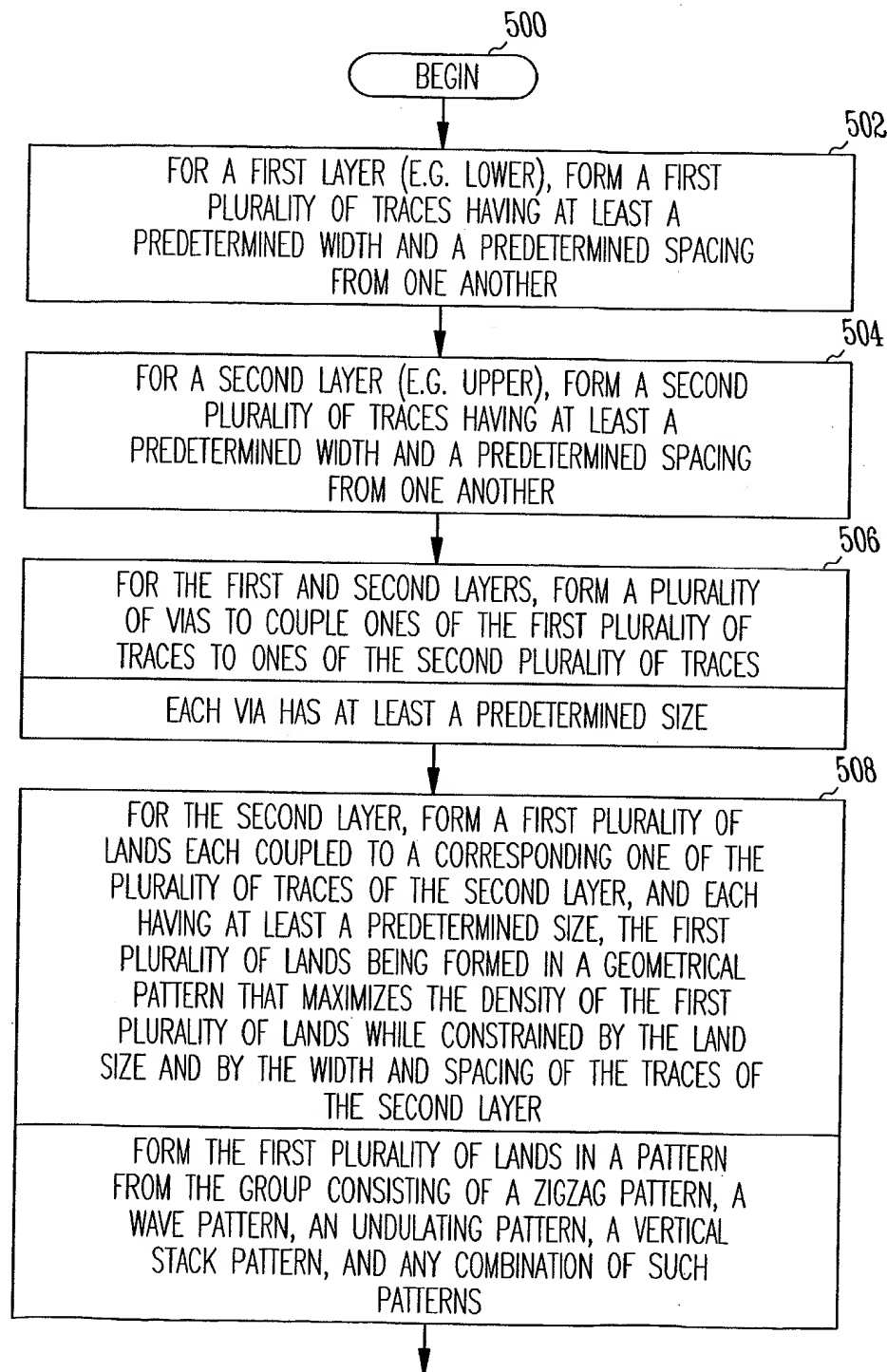


Fig. 11A

APPROVED	C.C. FIG.	TITLE:
BY	CLASS	SUBCLASS
DRAFTSMAN		

ELECTRONIC PACKAGE WITH HIGH DENSITY INTERCONNECT AND ASSOCIATED METHODS
 INVENTORS NAME: Tee Onn Chong et al.
 DOCKET NO.: 884.419US1

12/12

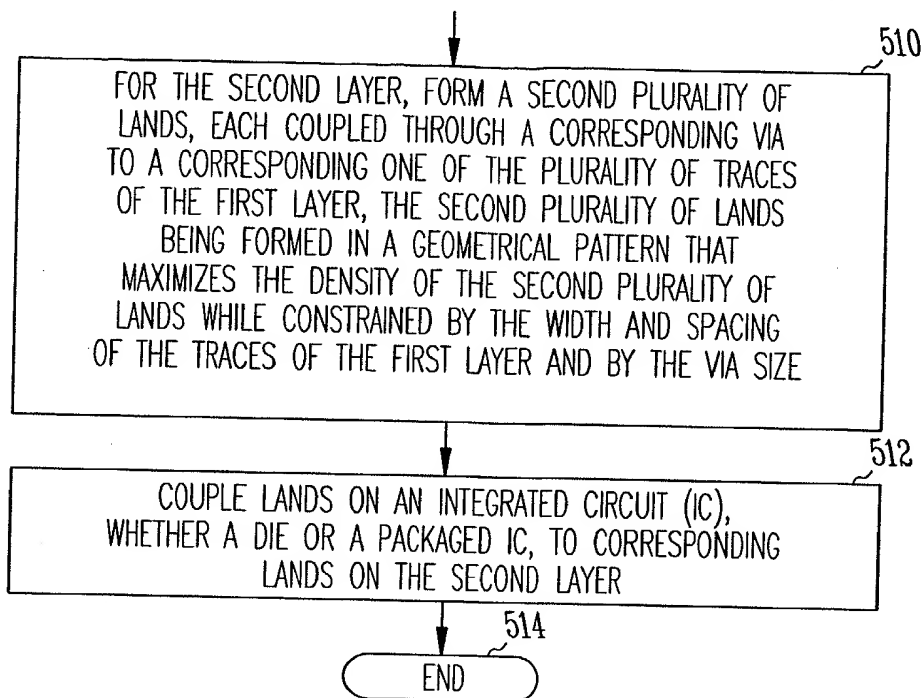


Fig. 11B

09858238-051501